

# Nch + Nch 30V 9.0A Small Signal MOSFET

V <sub>DSS</sub>	30V
R <sub>DS(on)</sub> (Max.)	16.0mΩ
I <sub>D</sub>	±9.0A
P <sub>D</sub>	2.6W

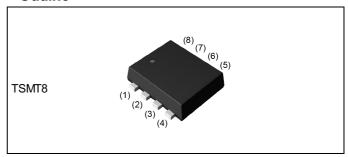
## Features

- 1) Low on resistance
- 2) Small Surface Mount Package (TSMT8)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen Free

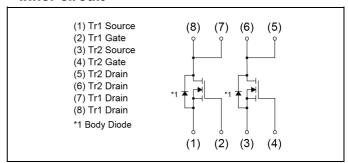
# Application

Switching

## Outline



## •Inner circuit



# Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TCR
	Marking	KA3

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	30	V
Continuous drain current	I <sub>D</sub> *1	±9.0	Α
Pulsed drain current	I <sub>DP</sub> *2	±18	Α
Gate - Source voltage	$V_{GSS}$	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	7.0	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	3.5	mJ
Down discipation (total)	P <sub>D</sub> *1	2.6	10/
Power dissipation (total)	P <sub>D</sub> *4	1.5	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Parameter	Cymbol	Values			Linit
- Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R <sub>thJA</sub> *4	ı	-	83.3	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Davanatas	Current ed	Conditions	Values Min. Typ.		Values		
Parameter	Symbol	Conditions			Max.	- Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 1mA$		-	-	V	
Breakdown voltage	ΔV <sub>(BR)DSS</sub>	I <sub>D</sub> = 1mA		21		mV/°C	
temperature coefficient	$\Delta T_{j}$	referenced to 25°C	-	21	-	IIIV/ C	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 30V, V_{GS} = 0V$	-	-	1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 1mA$		-	2.5	V	
Gate threshold voltage	$\Delta V_{GS(th)}$	I <sub>D</sub> = 1mA		-3		mV/°C	
temperature coefficient	ΔTj	referenced to 25°C	-	-3	-	IIIV/ C	
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 9A	-	12.3	16.0	m0	
on - state resistance	R <sub>DS(on)</sub> *5	$V_{GS} = 4.5V, I_D = 7A$	-	18.2	23.7	mΩ	
Gate resistance	$R_{G}$	f=1MHz, open drain	-	3.4	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 5V, I <sub>D</sub> = 7A	4.4	-	-	S	

<sup>\*1</sup> Pw ≤ 1s, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = 15V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Mounted on a ceramic board (30×30×0.8mm)

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Darameter	Symbol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	640	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15V	-	110	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	90	-	
Turn - on delay time	t <sub>d(on)</sub> *5	V <sub>DD</sub> ≈ 15V,V <sub>GS</sub> = 10V	-	8	-	
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 4.5A	-	19	-	no
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L = 3.3\Omega$	-	33	-	ns
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	7	-	

# ● Gate charge characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Daramatar	Cymahal	Conditions -		Values			1 1:4
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total meta abanna	O *5		V <sub>GS</sub> = 10V	-	15.5	-	
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 15V		-	7.9	-	<b>"</b> C
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 9A	V <sub>GS</sub> = 4.5V	-	3.1	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5			-	2.8	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

# <Tr1 and Tr2>

Parameter	Symbol Conditions		Values			- Unit	
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	1.0		
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	18	Α	
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A	-	-	1.2	V	

### Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

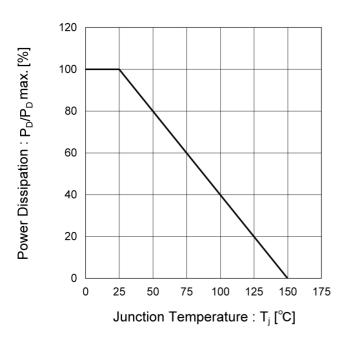
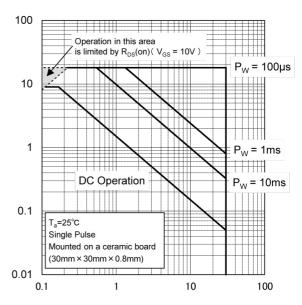


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

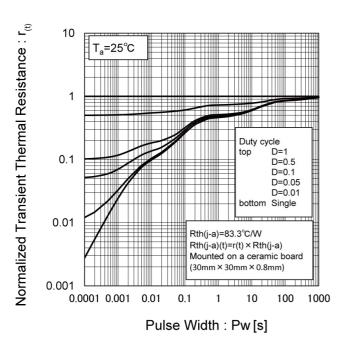
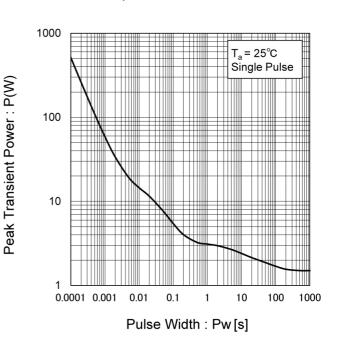


Fig.4 Single Pulse Maximum Power dissipation



Drain Current : I<sub>D</sub> [A]

### • Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

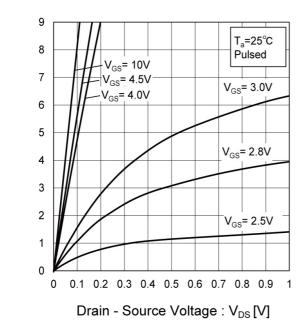
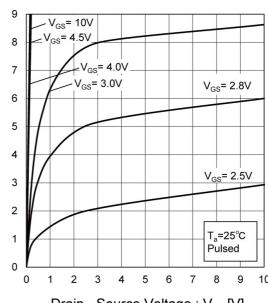


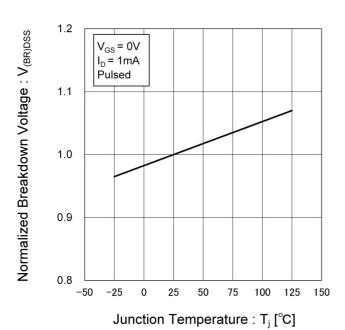
Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature



## • Electrical characteristic curves

Fig.8 Typical Transfer Characteristics

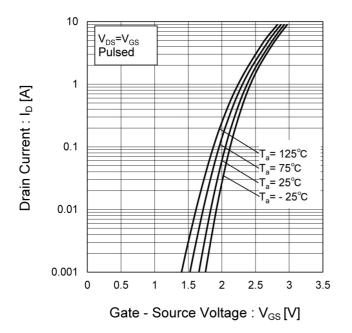


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

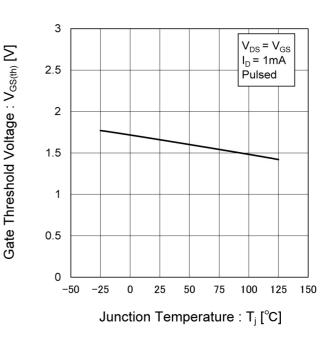
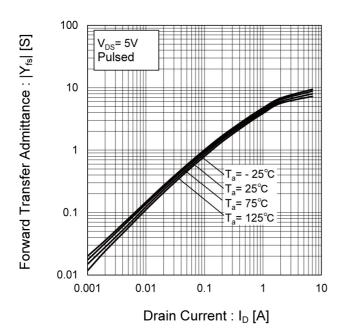


Fig.10 Forward Transfer Admittance vs.
Drain Current



## • Electrical characteristic curves

Fig.11 Drain Current Derating Curve

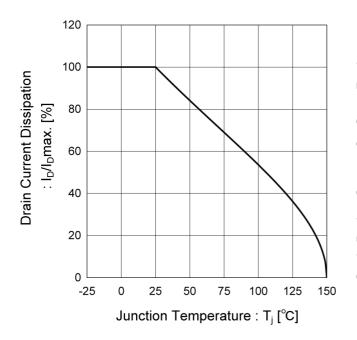


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

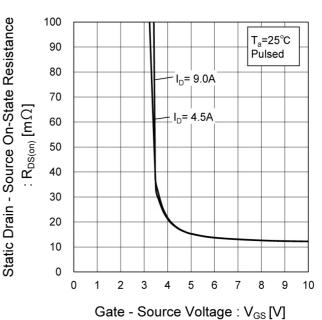
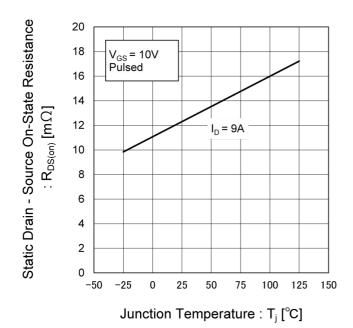


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



#### Electrical characteristic curves

Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

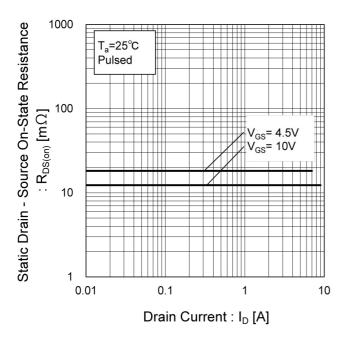
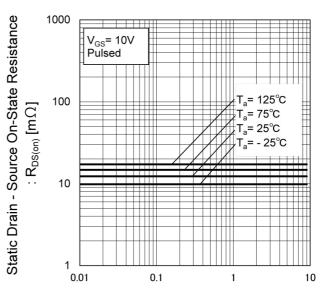
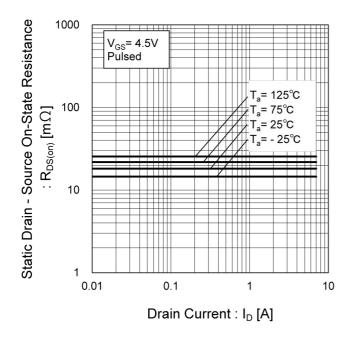


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)



Drain Current : I<sub>D</sub> [A]

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)



### • Electrical characteristic curves

Fig.17 Typical Capacitance vs.

Drain - Source Voltage

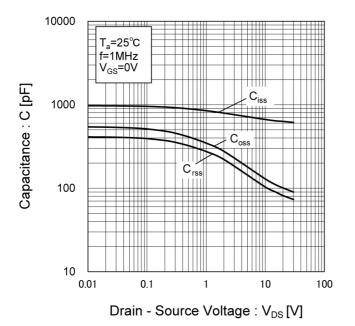


Fig.18 Switching Characteristics

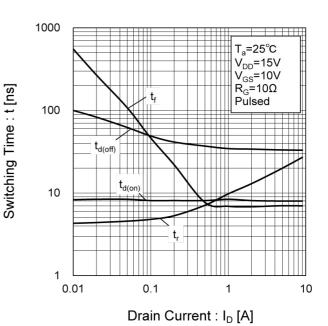


Fig.19 Dynamic Input Characteristics

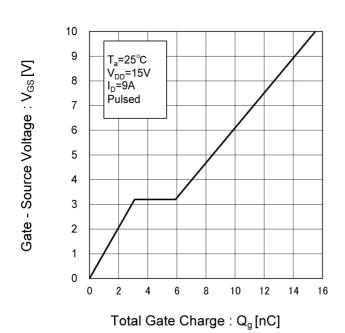
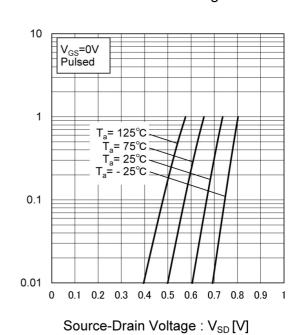


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

# • Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

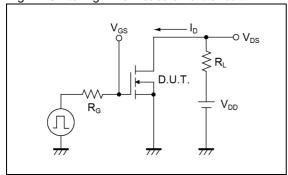


Fig.2-1 Gate Charge Measurement Circuit

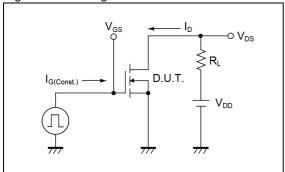


Fig.3-1 Avalanche Measurement Circuit

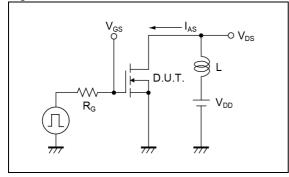


Fig.1-2 Switching Waveforms

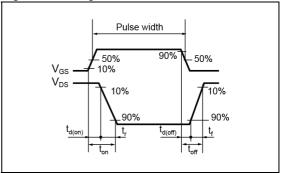


Fig.2-2 Gate Charge Waveform

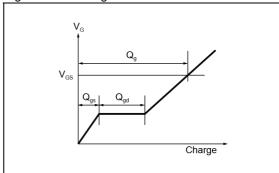
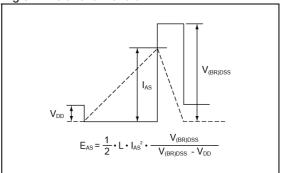


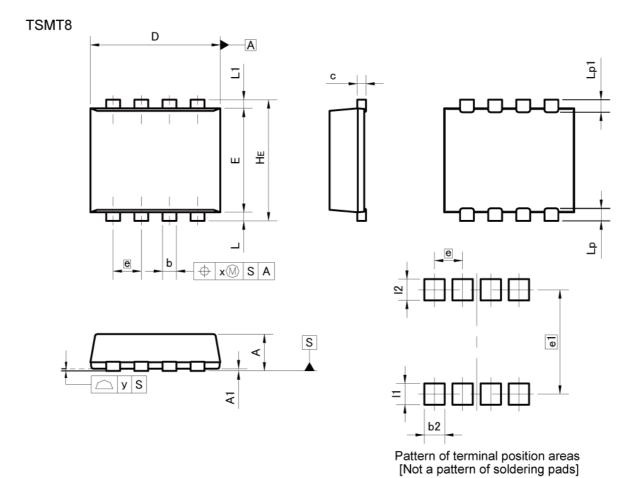
Fig.3-2 Avalanche Waveform



## Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

## Dimensions



DIM	MILIM	ETERS	TERS INCHE		
DIM	MIN	MAX	MIN	MAX	
Α	0.75	0.85	0.030	0.033	
A1	0.00	0.05	0.000	0.002	
b	0.27	0.37	0.011	0.015	
С	0.12	0.22	0.005	0.009	
D	2.90	3.10	0.114	0.122	
E	2.30	2.50	0.091	0.098	
е	0.	65	0.0	26	
HE	2.70	2.90	0.106	0.114	
L	0.10	0.30	0.004	0.012	
L1	0.10	0.30	0.004	0.012	
Lp	0.19	0.39	0.007	0.015	
Lp1	0.19	0.39	0.007	0.015	
х	ζ-	0.10	.=.	0.004	
У	-	0.10	2 <del></del> -	0.004	

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	-	0.47	-	0.019
e1	2.	41	0.0	95
I1	i –	0.49	-	0.019
12	1,-	0.49	-	0.019

Dimension in mm/inches

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(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCIII	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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